

Part Number: XZDGK60W

3.0mmx1.5mm SMD CHIP LED LAMP

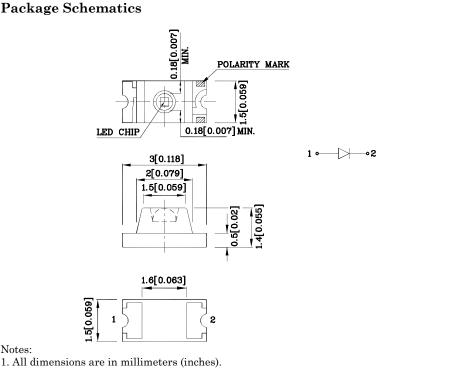
Features

- Ideal for indication light on hand held products
- Long life and robust package
- Standard Package: 2,000pcs/ Reel
- MSL (Moisture Sensitivity Level): 3
- RoHS compliant





ATTENTION OBSERVE PRECAUTIONS FOR HANDLING ELECTROSTATIC DISCHARGE SENSITIVE DEVICES



2. Tolerance is $\pm 0.2(0.008")$ unless otherwise noted.

Notes:

3. Specifications are subject to change without notice.

Absolute Maximum Ratings (T _A =25°C)	Green (InGaN)	Unit		
Reverse Voltage		5	V	
Forward Current	I_{F}	25	mA	
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	ifs	150	mA	
Power Dissipation	PD	102.5	mW	
Operating Temperature	$T_{\rm A}$	$-40 \sim +85$	°C	
Storage Temperature	Tstg	-40 ~ +85		
Electrostatic Discharge Threshold (HBM)	450	V		

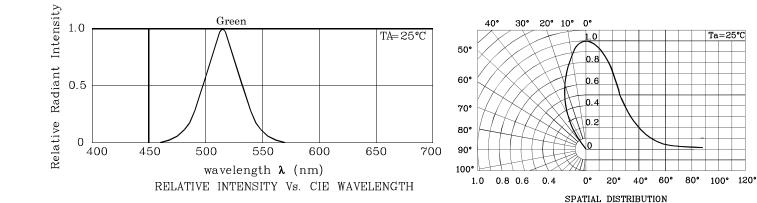
A Relative Humidity between 40% and 60% is recommended in ESD-protected work areas to reduce static build up during assembly process (Reference JEDEC/JESD625-A and JEDEC/J-STD-033)

Operating Characteristics (T _A =25°C)	Green (InGaN)	Unit		
Forward Voltage (Typ.) (I _F =20mA)	V_{F}	3.3	V	
Forward Voltage (Max.) (I _F =20mA)	$V_{\rm F}$	4.1	V	
Reverse Current (Max.) (V _R =5V)	I_R	50	uA	
Wavelength of Peak Emission CIE127-2007* (Typ.) (I _F =20mA)	λP	515*	nm	
Wavelength of Dominant Emission CIE127-2007* (Typ.) (I _F =20mA)	λD	525*	nm	
Spectral Line Full Width At Half-Maximum (Typ.) (I _F =20mA)	$ riangle\lambda$	35	nm	
Capacitance (Typ.) (V _F =0V, f=1MHz)	С	45	$_{\rm pF}$	

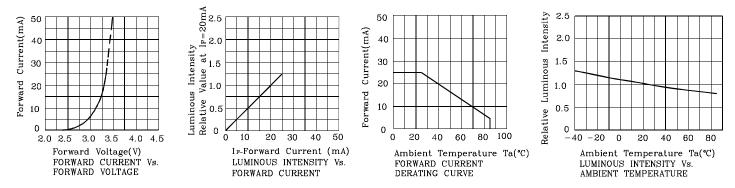
Part Number	Emitting Color	Emitting Material	Lens-color	Luminous CIE127 (I _F =20m		Wavelength CIE127-2007* λP nm	Viewing Angle 20 1/2
				min.	typ.		
XZDGK60W	Green	InGaN	Water Clear	500*	695*	515*	50°

*Luminous intensity value and wavelength are in accordance with CIE127-2007 standards.





Green



LED is recommended for reflow soldering and soldering profile is shown below.

300 (°C) 10 s max 250 4°C/s C/s max 200 150~180 4°C/s max 150 Temperature 30~50s 80~120: 100 50 0 150 0 50 100 200 250 300 (sec) Tim Notes:

Reflow Soldering Profile for SMD Products (Pb-Free Components)

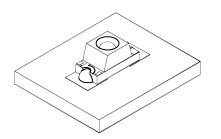
1. Maximum soldering temperature should not exceed 260°C

2. Recommended reflow temperature: 145°C-260°C 3. Do not put stress to the epoxy resin during

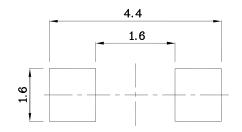
high temperatures conditions



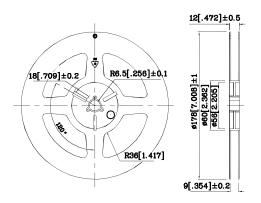
✤ The device has a single mounting surface. The device must be mounted according to the specifications.



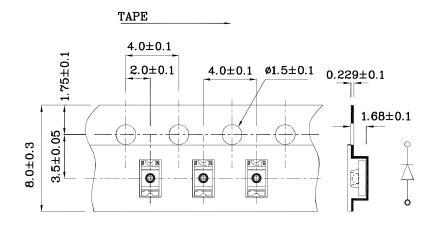
Recommended Soldering Pattern (Units : mm; Tolerance: ± 0.1)



Reel Dimension



Tape Specification (Units : mm)



Remarks:

If special sorting is required (e.g. binning based on forward voltage, Luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength: +/-1nm

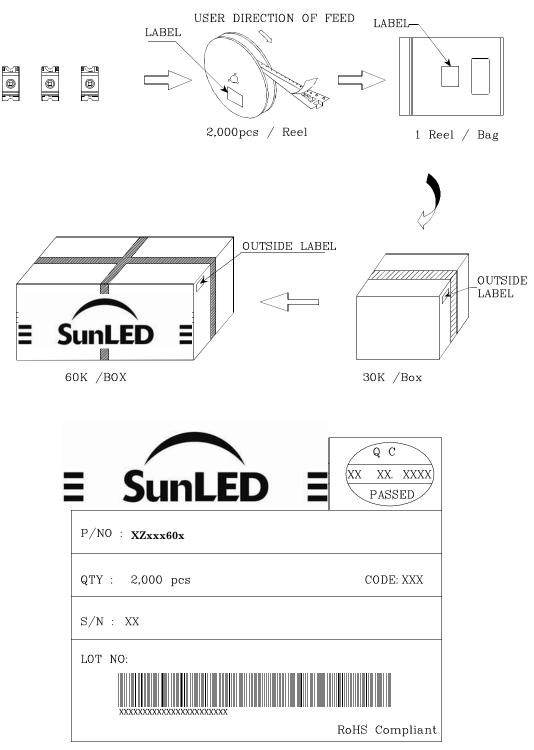
2. Luminous intensity / luminous flux: +/-15%

3. Forward Voltage: +/-0.1V $\,$

Note: Accuracy may depend on the sorting parameters.



PACKING & LABEL SPECIFICATIONS



TERMS OF USE

- 1. Data presented in this document reflect statistical figures and should be treated as technical reference only.
- 2. Contents within this document are subject to improvement and enhancement changes without notice.
- 3. The product(s) in this document are designed to be operated within the electrical and environmental specifications indicated on the datasheet. User accepts full risk and responsibility when operating the product(s) beyond their intended specifications.
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